



Title of Change:	Hydrazine elimination of ON Semiconductor Niigata Co., Ltd. (OSNC) and change to copper wire material.																			
Proposed first ship date:	22 November 2018																			
Contact information:	Contact your local ON Semiconductor Sales Office or < Tetsuya.Fukushima@onsemi.com >																			
Samples:	Contact your local ON Semiconductor Sales Office.																			
Type of notification:	<p>This is an Initial Product/Process Change Notification (IPCN) sent to customers. IPCNs are issued at least 30 days prior to the issuance of the Final Change Notice (FPCN). An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.</p> <p>The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>.</p>																			
Change Part Identification:	Date Code																			
Change category:	<input checked="" type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____																			
Change Sub-Category(s):	<input type="checkbox"/> Manufacturing Site Change/Addition <input checked="" type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input checked="" type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Other: _____																			
Sites Affected:	ON Semiconductor Sites: ON Carmona, Philippines ON Niigata, Japan	External Foundry/Subcon Sites: None																		
Description and Purpose:																				
<p>This Initial notification announces the elimination of Hydrazine in ON Semiconductor Niigata Co., Ltd. (OSNC) Japan for parts listed in this PCN.</p> <p>The related products are transferred to a process that does not use Hydrazine on the same site OSNC. In addition, change the connection between the chip and the lead from Gold wire to Copper wire.</p>																				
	<table border="1"> <thead> <tr> <th>Change Point</th> <th>Before Change Description</th> <th>After Change Description</th> </tr> </thead> <tbody> <tr> <td>Fab (OSNC)</td> <td>N1 Fab (Minimum rule=0.8um, Class=100)</td> <td>N1 Fab (Minimum rule=0.8um, Class=100) AND N2 Fab (Minimum rule=0.25um, Class=10)</td> </tr> <tr> <td>Wire material</td> <td>Aluminum (without Anti-reflected Layer)</td> <td>Aluminum (with Anti-reflected Layer)</td> </tr> <tr> <td>Interlayer material</td> <td>Silicon nitride and Polyimide or Polyimide</td> <td>Silicon nitride and Silicon oxide or Oxide</td> </tr> <tr> <td>Package wire material</td> <td>Gold wire</td> <td>Copper wire</td> </tr> <tr> <td>Mold Compound</td> <td>G600</td> <td>G700</td> </tr> </tbody> </table>		Change Point	Before Change Description	After Change Description	Fab (OSNC)	N1 Fab (Minimum rule=0.8um, Class=100)	N1 Fab (Minimum rule=0.8um, Class=100) AND N2 Fab (Minimum rule=0.25um, Class=10)	Wire material	Aluminum (without Anti-reflected Layer)	Aluminum (with Anti-reflected Layer)	Interlayer material	Silicon nitride and Polyimide or Polyimide	Silicon nitride and Silicon oxide or Oxide	Package wire material	Gold wire	Copper wire	Mold Compound	G600	G700
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Qualification Plan:

QV DEVICE NAME: LB11870-TRM-E
 PACKAGE: HSSOP48 (375 mil)

Test	Specification	Condition	Interval
HTOL	JESD22-A108	Tj=150°C, 100 % max rated Vcc	1008 hrs
HTSL	JESD22-A103	Ta= 150°C	1008 hrs
TC	JESD22-A104	Ta= -65°C to +150°C	500 cyc
THB	JESD22-A101	85°C, 85% RH, bias	1008 hrs
uHAST	JESD22-A118	130°C, 85% RH, 18.8psig,	96 hrs
PC	J-STD-020 JESD-A113	MSL 3 @ 260 °C	-
HBM	JS001	100pF,1.5kohm	-
CDM	JS002		-

List of Affected Standard Part:

Part Number	Qualification Vehicle
LB1909MC-BH	LB11870-TRM-E



Appendix A: Changed Products

Product	Customer Part Number	Qualification Vehicle
LB1909MC-BH		LB11870-TRM-E